

Ultralow Power Silicon Microdisk Modulators and Switches

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9/17/2008**

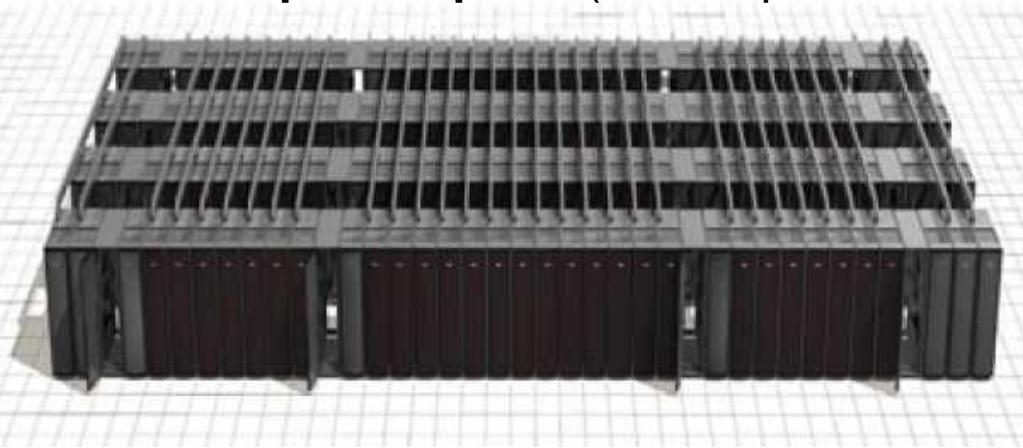
**Sandia National Labs, Albuquerque NM
Applied Photonic Microsystems**

Motivation: Power / Bandwidth in Supercomputers

"Based on current trends, by 2011 data center energy consumption will nearly double again, requiring the equivalent of 25 power plants. The world's data centers, according to recent study from McKinsey & Company, could well surpass the airline industry as a greenhouse gas polluter by 2020."

Quote from "Demand for Data Puts Engineers in Spotlight," New York Times, June 17, 2008

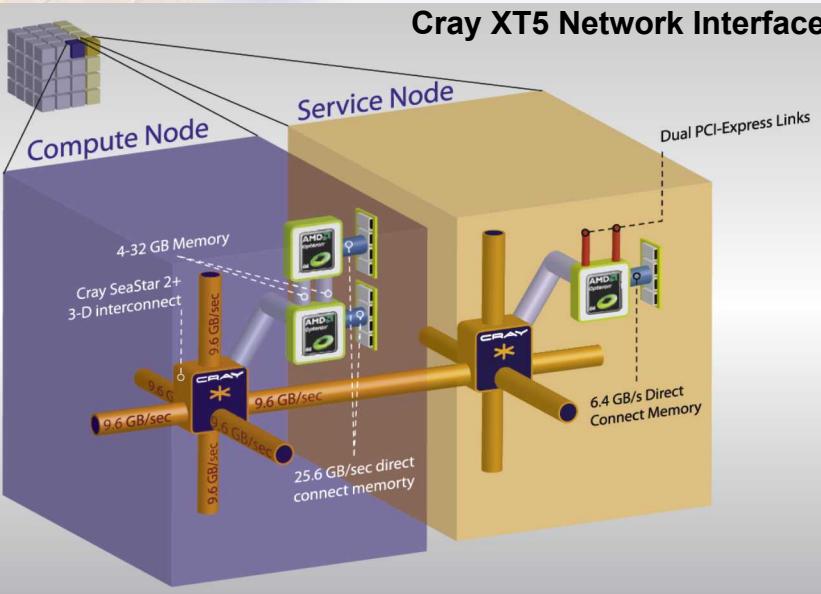
Sandia's Red Storm Supercomputer (26,569 processor cores, ~3.5MW power)



- Question:** Now at 1PFLOPs, what does it take to get to 1-ExaFLOPs?
- Power:** Hoover Dam provides ~1GW . . . what will future supercomputers need?
- Bandwidth:** To scale real-world application performance, communications must scale with compute performance (i.e. bytes/FLOP ~ 1 Bidirectional)



Interconnect Requirements for Super-Computers



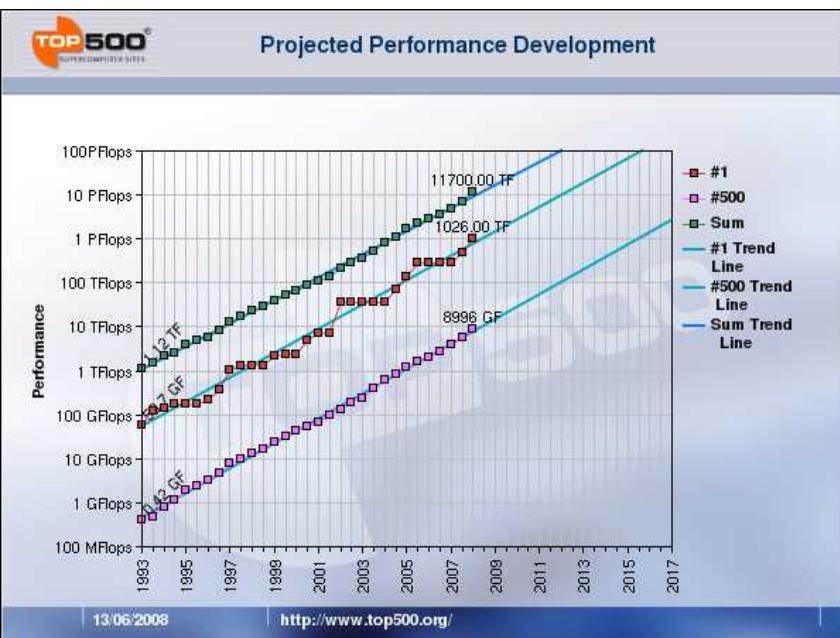
Today (2008)

- **BW/node:** $14 \times 9.6 \text{GB/s} \rightarrow 1.08 \text{Tb/s/node}$
- **BW/core:** 1.08Tb/s (Red Storm, originally)
 - now BW/core is $\sim 250 \text{Gb/s}$
- Top machines achieve $\sim 1 \text{PFLOPs}$ peak

Future (2018)

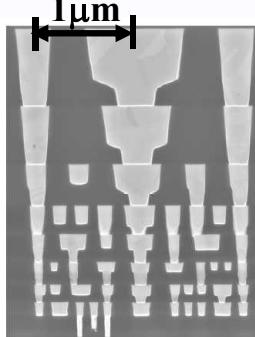
- By 2018 DOE expects to reach 1-ExaFLOPs
- ITRS projects we will reach 14nm node
- Cores/chip > 100 , conservatively
- $100 \text{cores/chip} \times 1.08 \text{Tb/s/core} = 108 \text{Tb/s/chip}$

Can the bandwidth requirements be achieved with electrical signaling at reasonable power levels?



Can Electronics meet BW Requirements?

IBM 65nm Process Metal

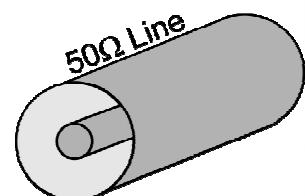


Intrachip Electrical: Charged Lines

- Energy: $CV_0^2/4 \rightarrow \sim 0.5 \text{pJ/bit/cm}$ (50W for 100Tb/s)
- Bandwidth: Achieve $\sim 1 \text{Gb/s}/1 \mu\text{m} \rightarrow 10 \text{Tb/s/cm/layer} \rightarrow 10 \text{ layers}$
- Conclusion: On-chip electrical signaling is troublesome in 2020

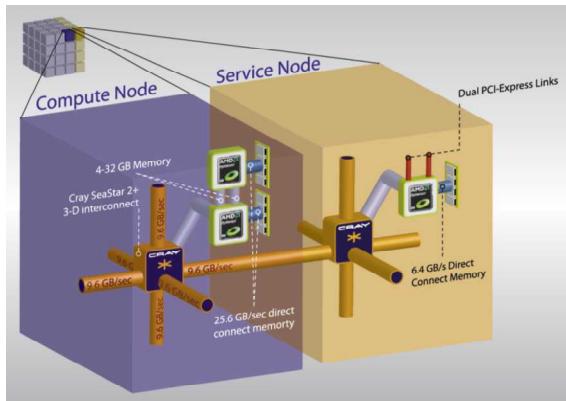
Interchip Electrical: Transmission Lines

- Energy: $\tau V_0^2/2Z_0 \rightarrow \sim 10 \text{pJ/bit}$ (50Ω line, 1ns pulse, 1-Volt signal)
 - Chip Comm. Power: $100 \text{Tb/s} \times 10 \text{pJ/bit} \rightarrow 1 \text{kW/chip}$
 - System Comm. Power: 1-ExaFLOPs $\rightarrow 3.2 \text{GW Communications Power}$
- Bandwidth
 - Board: 10Gb/s/mm/layer (1000 layers $\rightarrow 100 \text{Tb/s}$)
 - Pins-to-board: $10 \text{Gb/s} \rightarrow 10000 \text{ pins/chip} \rightarrow 100 \text{Tb/s}$
 - Inter-Rack: 10000 wires/chip, 1000-chips/rack $\rightarrow 10 \text{M wires/rack}$
- Conclusion: Logistically, off-chip electrical signaling becomes impossible, power consumption is out of control!!!

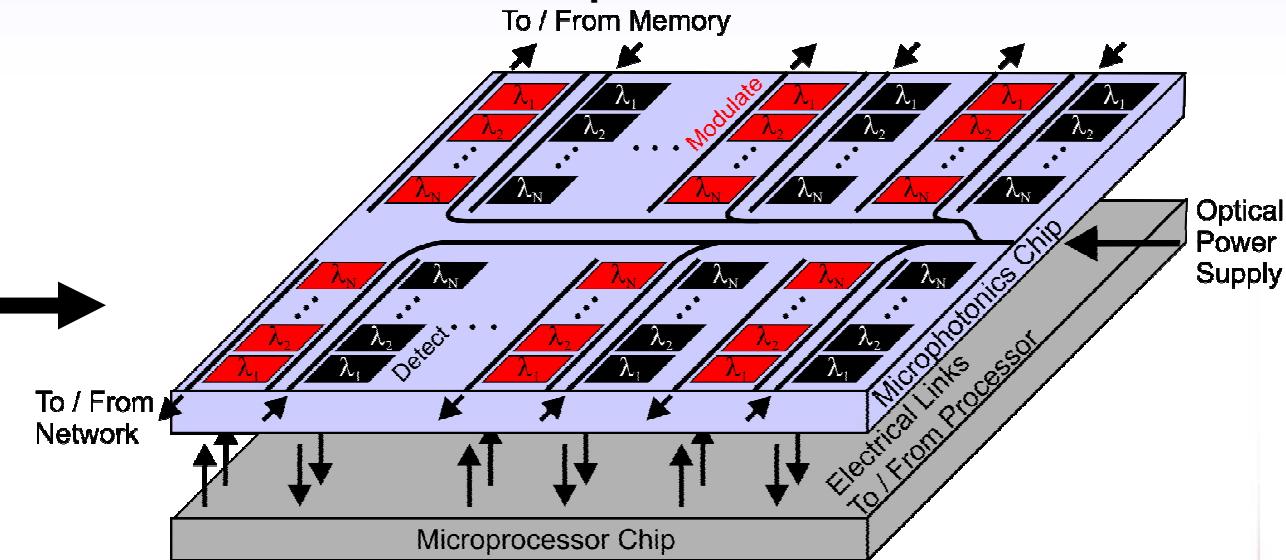


What about an Optical Network Interface?

Electrical Network Interface



Microphotonic Network Interface



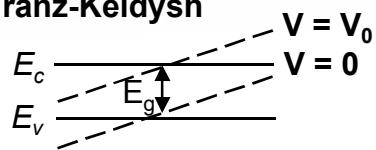
Optical Communications (Tightly Integrated with CMOS)

- **Energy = $h\nu V_0 C / (\eta q)$**
 - Receiver: **<1fJ/bit** required to flip a gate (Miller, 1989)
 - Modulator: Limited by capacitance (can get below **10fJ/bit**)
- **Bandwidth**
 - Optical bandwidth: $>1\text{-Tb/s}$ (10Gb/s @100λ's), 50GHz spacings → **5THz (40nm)**
 - Bandwidth (on-chip): $> 200\text{Gb/s}/\mu\text{m}$ → **1Tb/s on a 5um pitch**
 - Bandwidth (off-chip) $> \sim 10\text{Tb/s/mm}$ (**10mm → 100Tb/s**)
 - Routing of data could be O-E-O or in the optical domain . . .

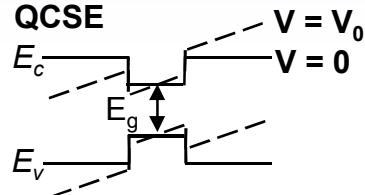
Possible Effects in Si/Ge Systems

Band-Edge Effects (Electro-Absorption $\Delta\alpha$)

Franz-Keldysh

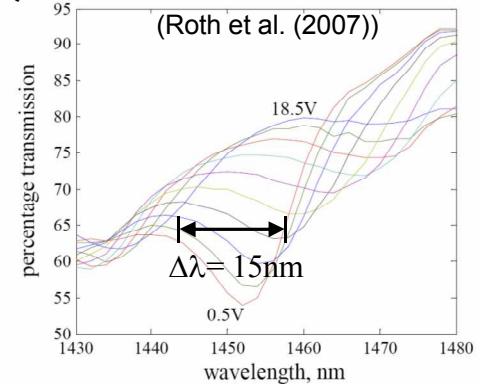


QCSE



- Franz-Keldysh (Liu et al. *NP*, July 2008)
- Quantum Confined Stark (Roth et al. *OE*, April 2007)
- **Advantage:** Strong effect \rightarrow small, low power devices (Liu claims 50fJ/bit)
- **Disadvantages:** \rightarrow Limited Optical Bandwidth ($\Delta\lambda = 10\text{nm-to-}15\text{nm}$)
Limited Contrast ($\Delta\alpha/\alpha \sim 3$), Intricate Fabrication

Quantum Confined Stark Effect

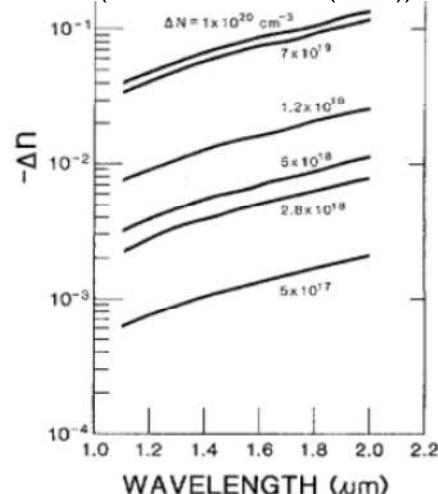


Free-Carrier Effect (Electro-Refraction Δn)

- **Advantages:** Broadband effect ($\Delta\lambda \gg 100\text{nm}$),
easy CMOS implementation
- **Disadvantages:** Weaker effect \rightarrow
need resonance for low energy/bit,
but already have thousands of
resonators on-chip

Free-Carrier Effect

(Soref and Bennett (1987))

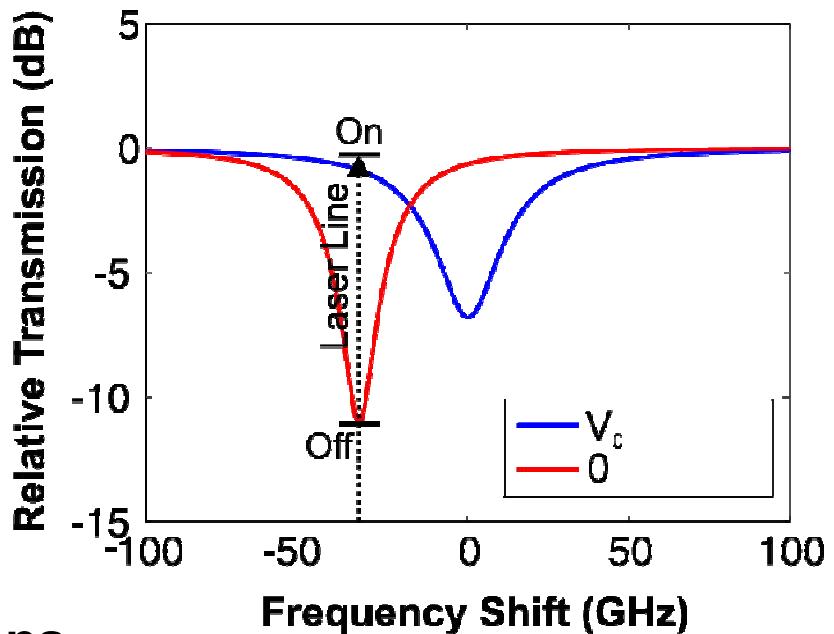
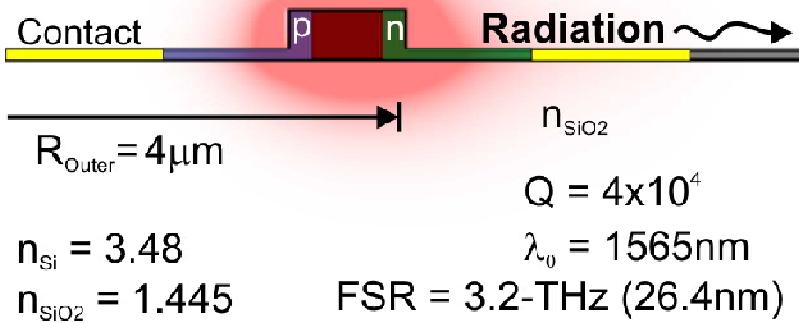


Silicon Modulators

Prior Art

- Liu (R-biased MZ 2004), Green (F/R-biased MZ 2007), Xu (F-biased Ring, 2005), etc.
- Note: Forward biased structures all require pre-emphasis to reach 10Gb/s

Theoretical Minimum Ridge Modulator Size (not yet demonstrated)



Goals

- 10Gb/s operation
- Low Power
- Large optical bandwidth

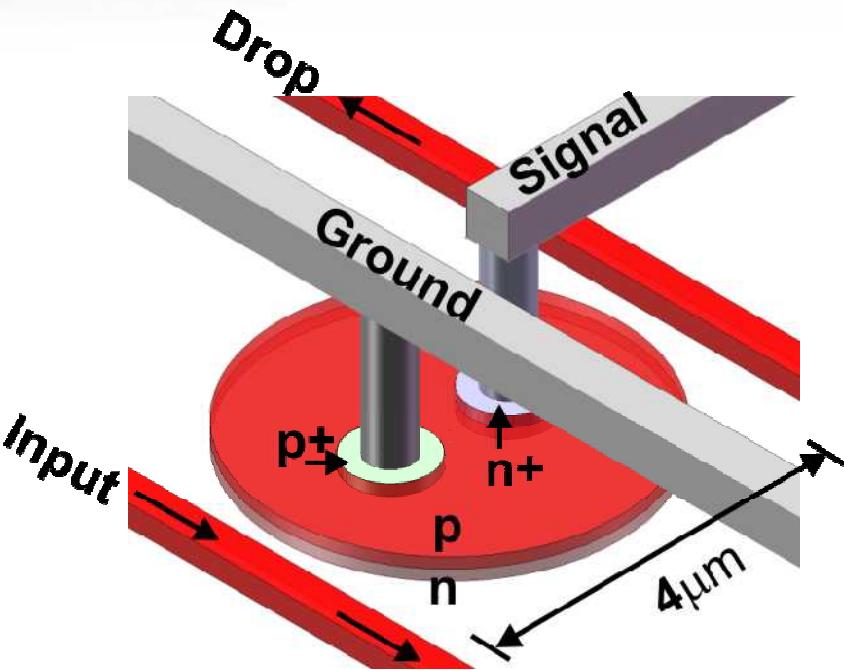


Solutions

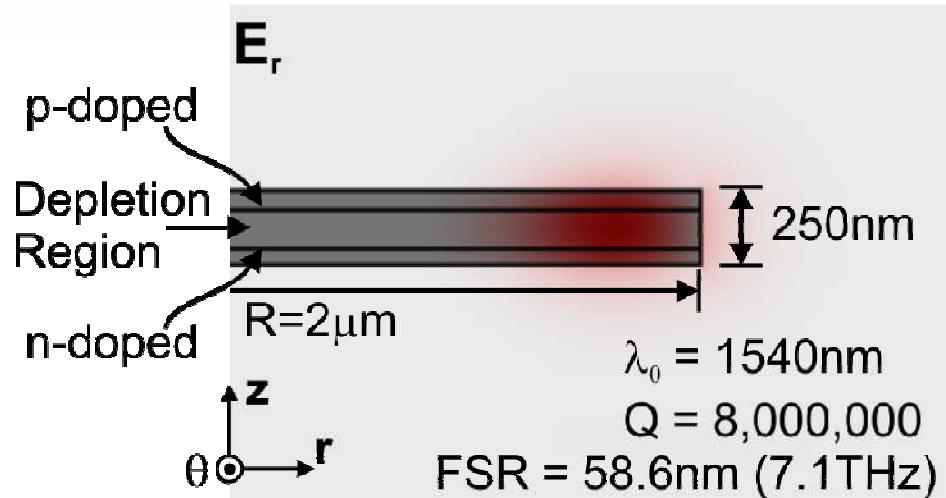
- Reverse-Biased (no carrier lifetime issue)
- Reverse-Biased, Large Overlap with Mode
- Small Disk/Ring (no ridge) for Large FSR

Microdisk Modulators: Design & Simulation

Vertical P-N Junction



TE₁₁ Cylindrical Mode

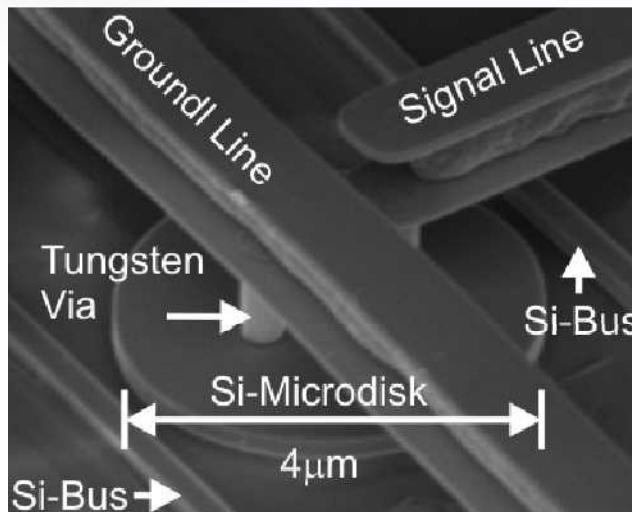


Advantages of a Vertical P-N Junction Modulator

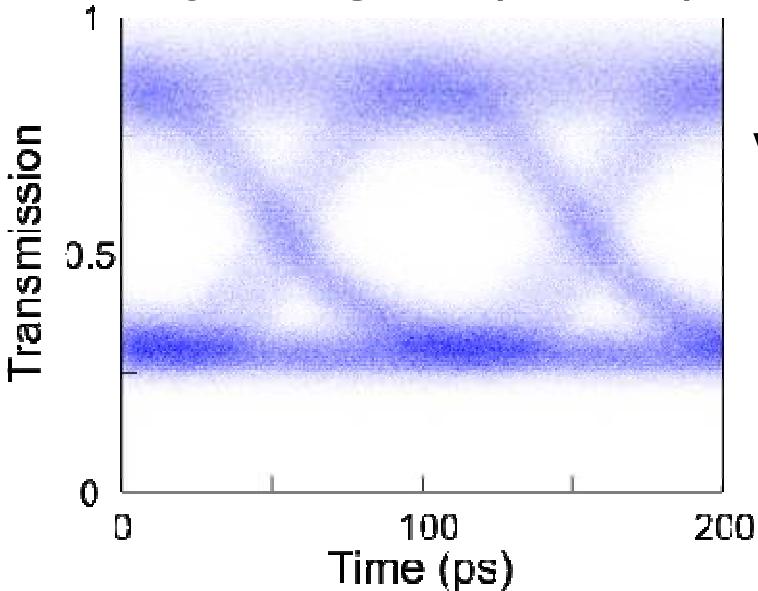
- Vertical P-N junction enables tighter confinement and greater modal overlap with depletion region
- Devices as small as $R = 1.5 \mu\text{m}$ are possible
- Huge Free-Spectral-Range (> 9 THz possible w/ $R=1.5 \mu\text{m}$)
- Smaller devices, no pre-emphasis → faster / lower power

Microdisks Modulator Demonstration

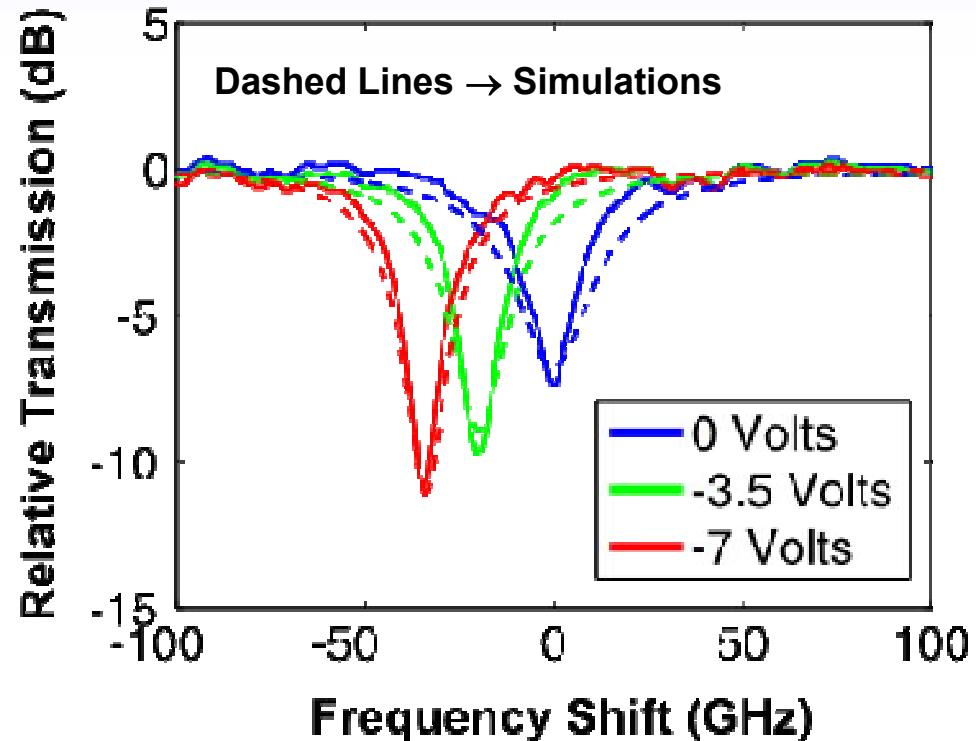
SEM of the Microdisk



Eye Diagram (10Gb/s)



Frequency Shift vs. Reverse Bias

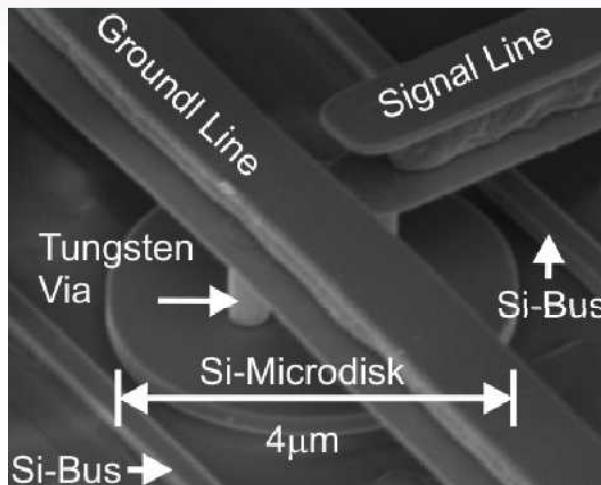


Vertical Junction Reverse-Biased Results

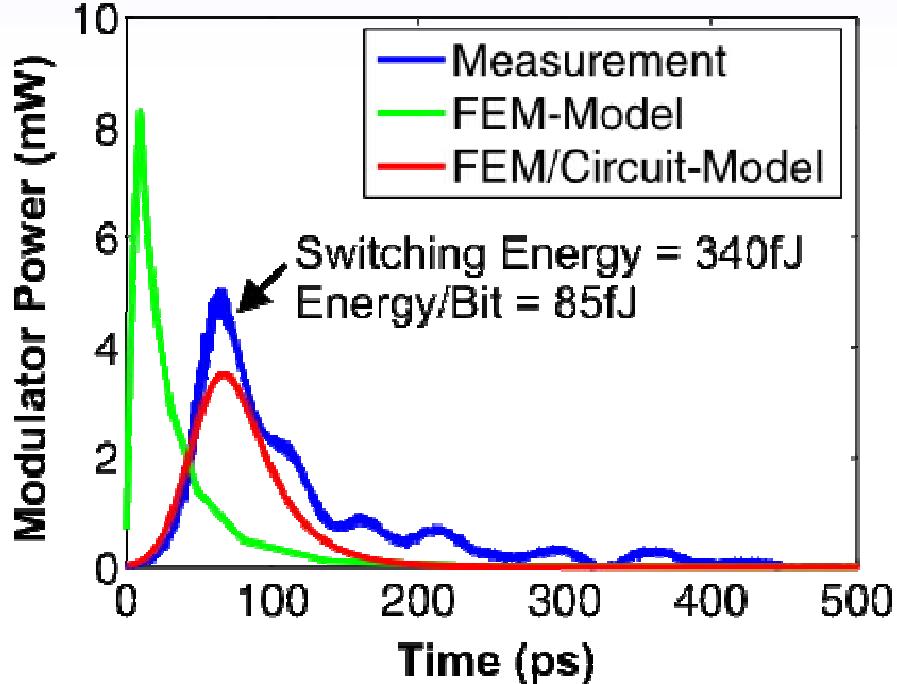
- ❑ 35-GHz freq. shift demo'ed, >70-GHz possible
- ❑ Achieved a $\text{BER} < 10^{-12}$ at 10Gb/s
- ❑ First resonant modulator with CMOS compatible drive (1.8V incident, ~3.5V due to reflection)

Power Efficiency Measurement (energy/bit)

SEM of the Microdisk



TDR Measurement vs. Simulations

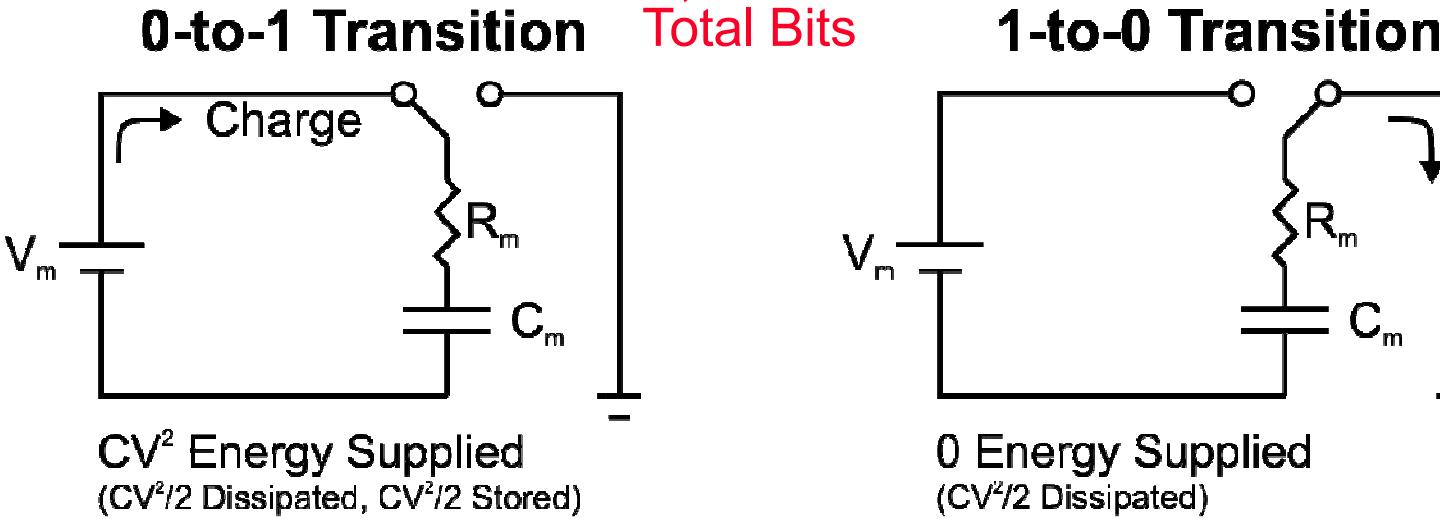


Time Domain Reflectometry Measurement Results (@3.5V)

- ❑ Reverse-biased approach dissipates essentially no static power
- ❑ Switching Energy = 340fJ
- ❑ PRBS Energy/Bit = Switching Energy/4 = 85fJ (**100X less than electrical**)
- ❑ New designs indicate ~10fJ/bit is possible

Energy/Bit in a Capacitive Modulator

Definition: $Energy / Bit = \frac{1}{BR \cdot T} \int_0^T P(t) dt$, where $BR = Bit\ Rate$

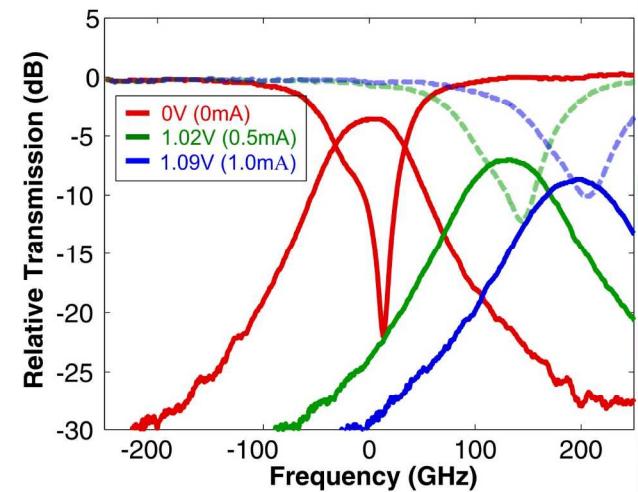
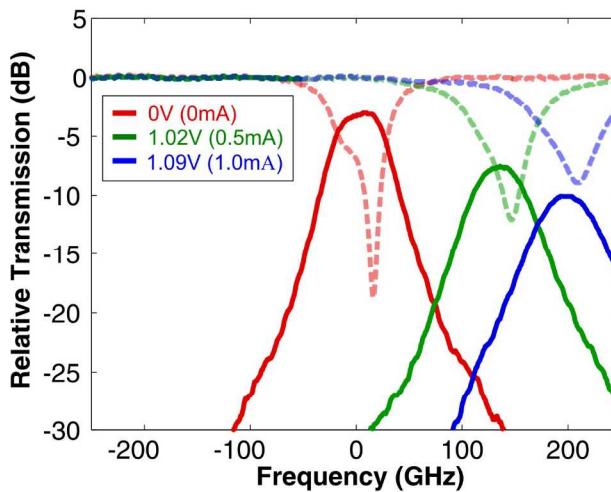
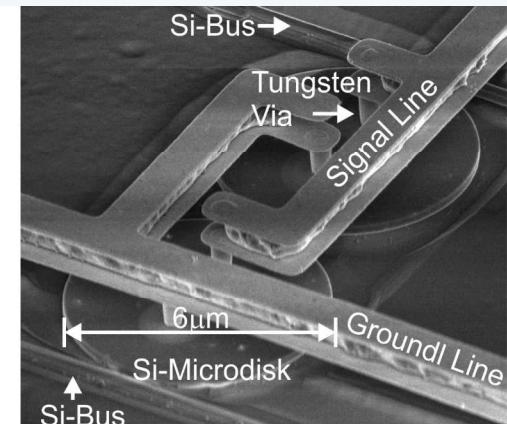
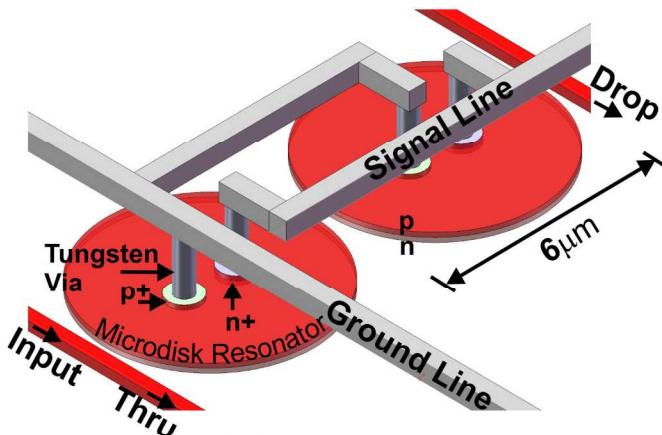


- **Switching Energy:** $E_s = CV^2$ ($CV^2/2$ dissipated, $CV^2/2$ stored)
- **Clocking Energy/"Bit":** $CV^2/2$ (because 0-1-0-1-0-1, etc.)
- $$E(\text{energy/bit}|0) = P(0-1|0\text{-state}) * \text{energy}_{\text{diss}}(0-1) + P(0-0|0\text{-state}) * \text{energy}_{\text{diss}}(0-0)$$
$$= 0.5 * CV^2/2 + 0.5 * 0 = CV^2/4$$
- $$E(\text{energy/bit}|1) = P(1-0|1\text{-state}) * \text{energy}_{\text{diss}}(1-0) + P(1-1|1\text{-state}) * \text{energy}_{\text{diss}}(1-1)$$
$$= 0.5 * CV^2/2 + 0.5 * 0 = CV^2/4$$
- **PRBS E(energy/bit)** = $P(0) * E(\text{energy/bit}|0) + P(1) * E(\text{energy/bit}|1) = CV^2/4$
- *So, Liu et al., you may have a 25fJ/bit modulator*

Reconfigurable Networks: Bandpass Switch

Demonstration

- 1st demonstration of high-speed, electrically active, silicon bandpass switches
- Completely shift resonator bandpass out of the channel



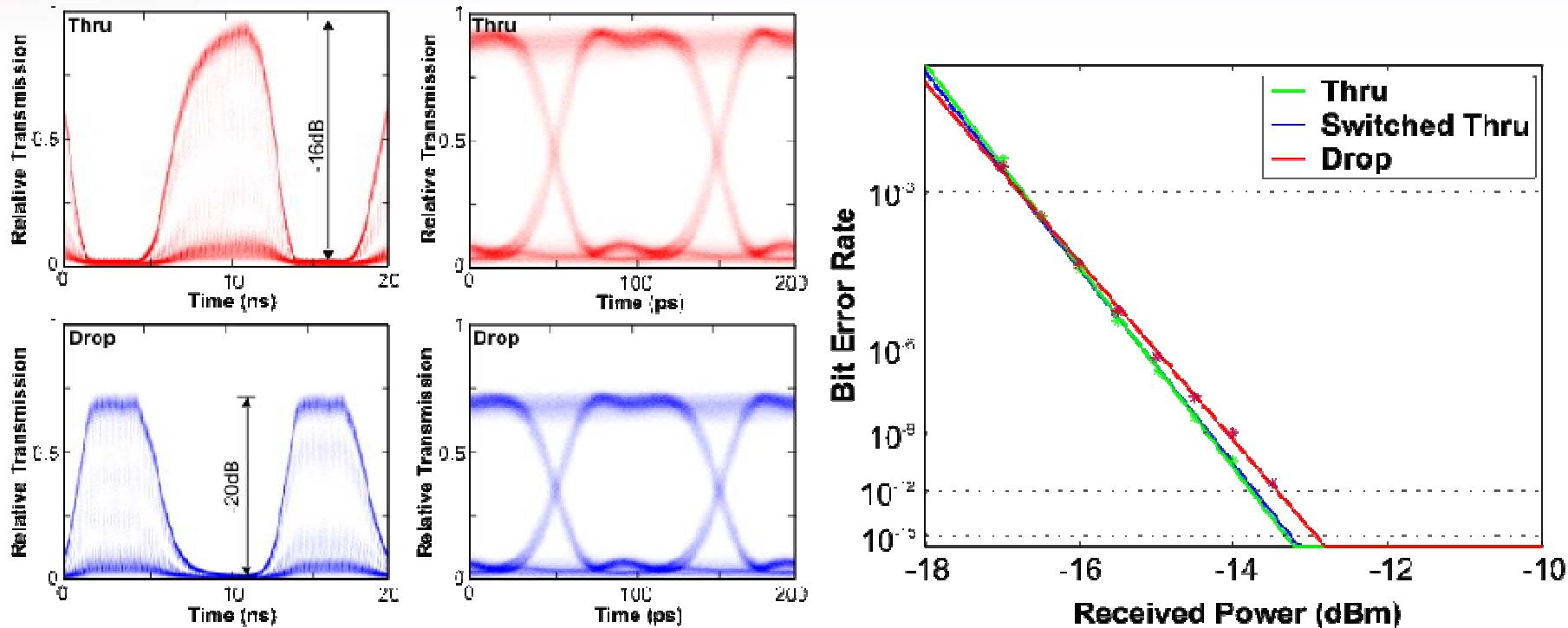
Benefits

- Potential for ultralow power switching in the optical domain (to avoid OEO conversions)

M. R. Watts *et al.*, OFC Postdeadline Presentation (Feb. 2008)

Note: Optically Active Switch Based on Q-Switching by Y. Vlasov *et al.*, Nature Photonics (Mar. 2008)

Data Routing with Bandpass Switch



Switch Results

- Data switched error-free ($BER < 10^{-12}$) with little power with ~ 2 ns rise time
- Power penalty measured to be < 0.4 dB in Drop Port and < 0.1 dB in Thru Port
- Driven with ~ 0.6 V (~ 1 V due to reflection), so CMOS compatible



Quick Review

Modulators

- Demonstrated, smallest, highest speed, lowest energy/bit (100X less energy/bit than electrical), and lowest voltage resonant silicon modulators

Bandpass Switches

- First, high-speed silicon bandpass switches
- Requires ~1V to shift bandpass by ~200GHz

Optical-Electrical-Optical or Optical Domain Routing?

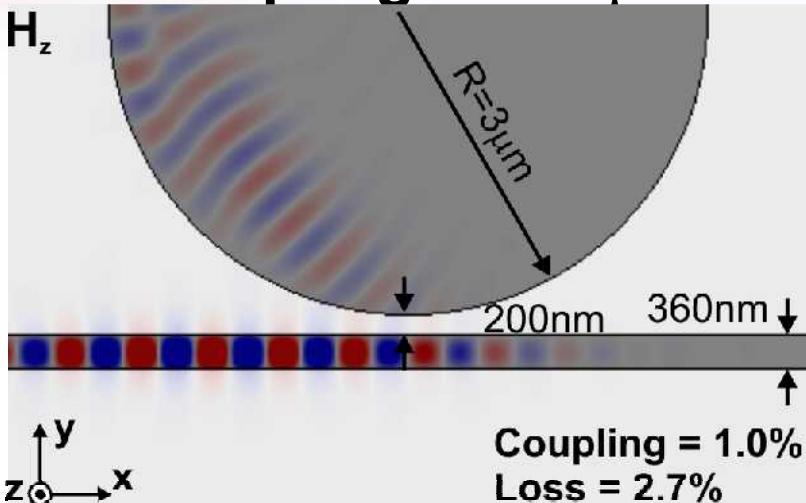
- Both approaches are possible. Modulators and bandpass switches form the beginnings of a suite of available networking components

Still, there are some problems with microdisks . . .

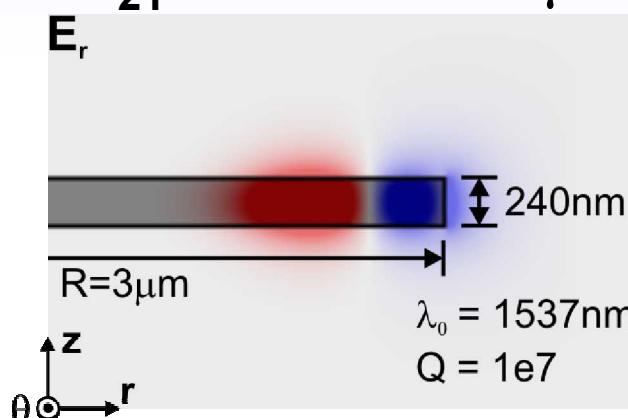


Problem 1: Coupling Losses

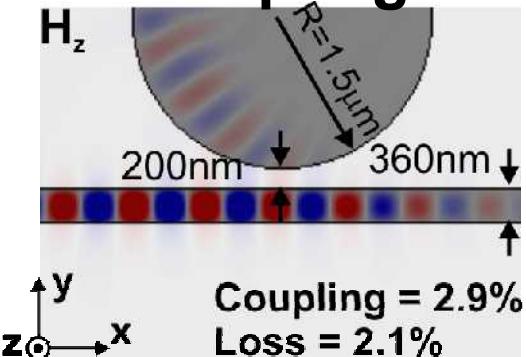
TE Coupling: $R = 3\mu\text{m}$



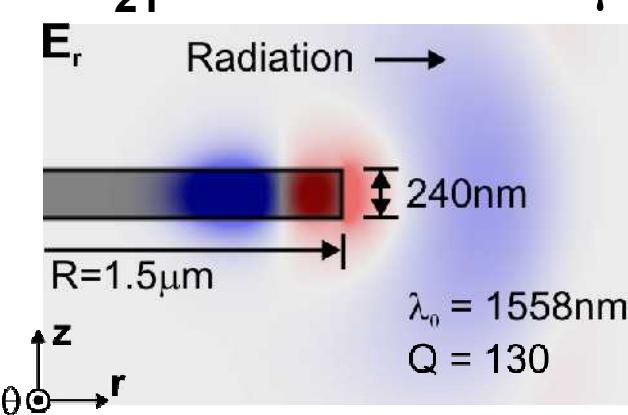
TE₂₁ Mode: $R = 3\mu\text{m}$



TE Coupling: $R = 1.5\mu\text{m}$



TE₂₁ Mode: $R = 1.5\mu\text{m}$



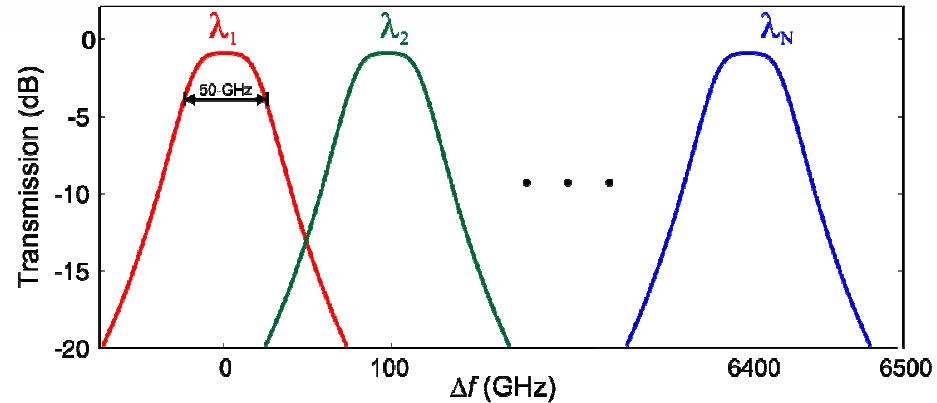
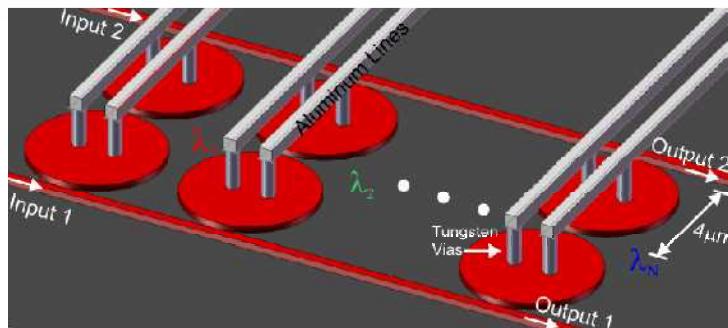
Important Considerations

- Smaller disk \Rightarrow Lower coupling loss? Why?
- Secondary mode can be cut-off, but requires very small disks

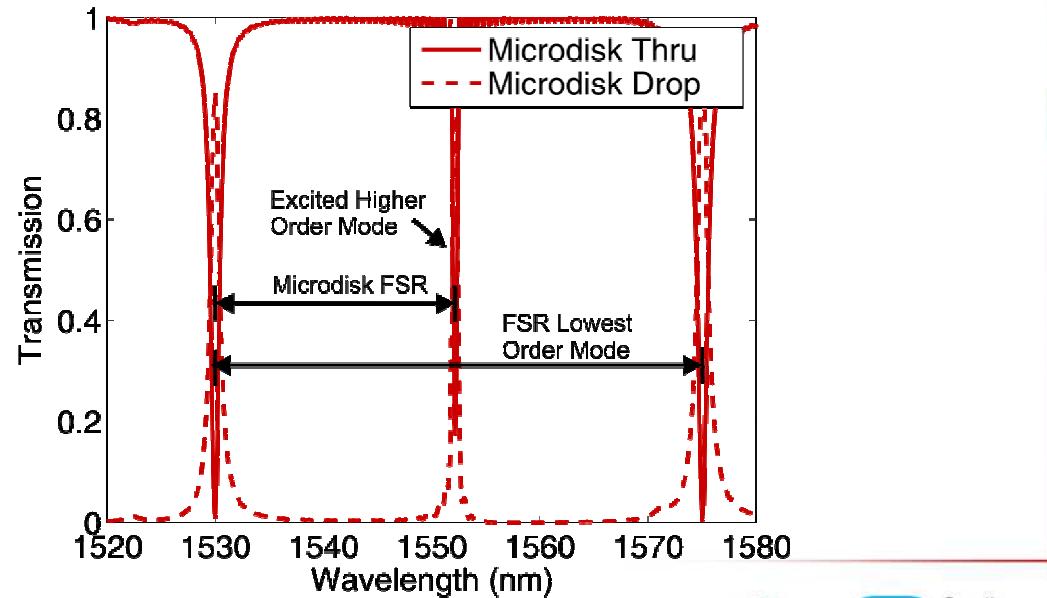
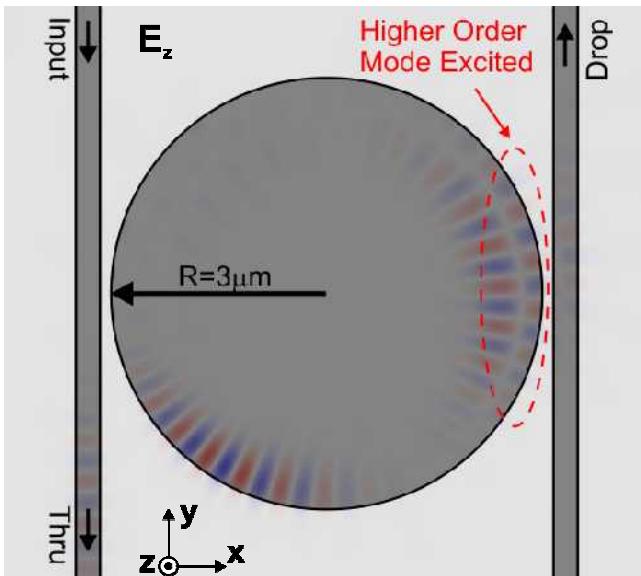


Problem 2: Limited Free-Spectral Range

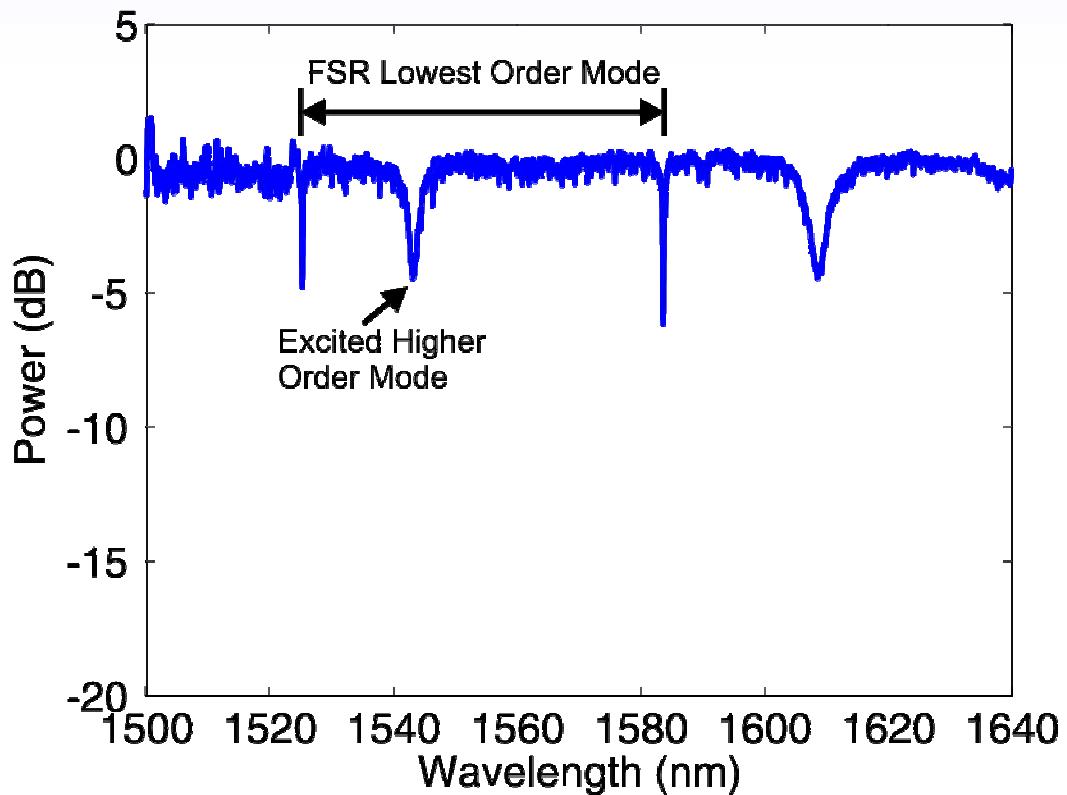
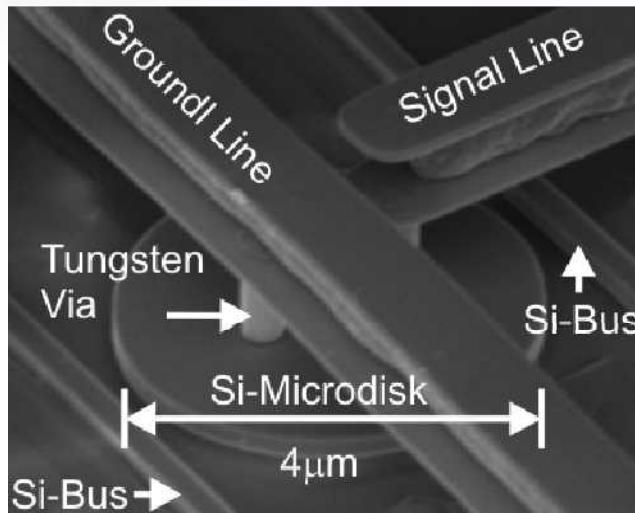
Goal: Large channel count, large bandwidth \rightarrow Large FSR



Problem: Microdisks propagate multiple spatial modes, corrupting FSR



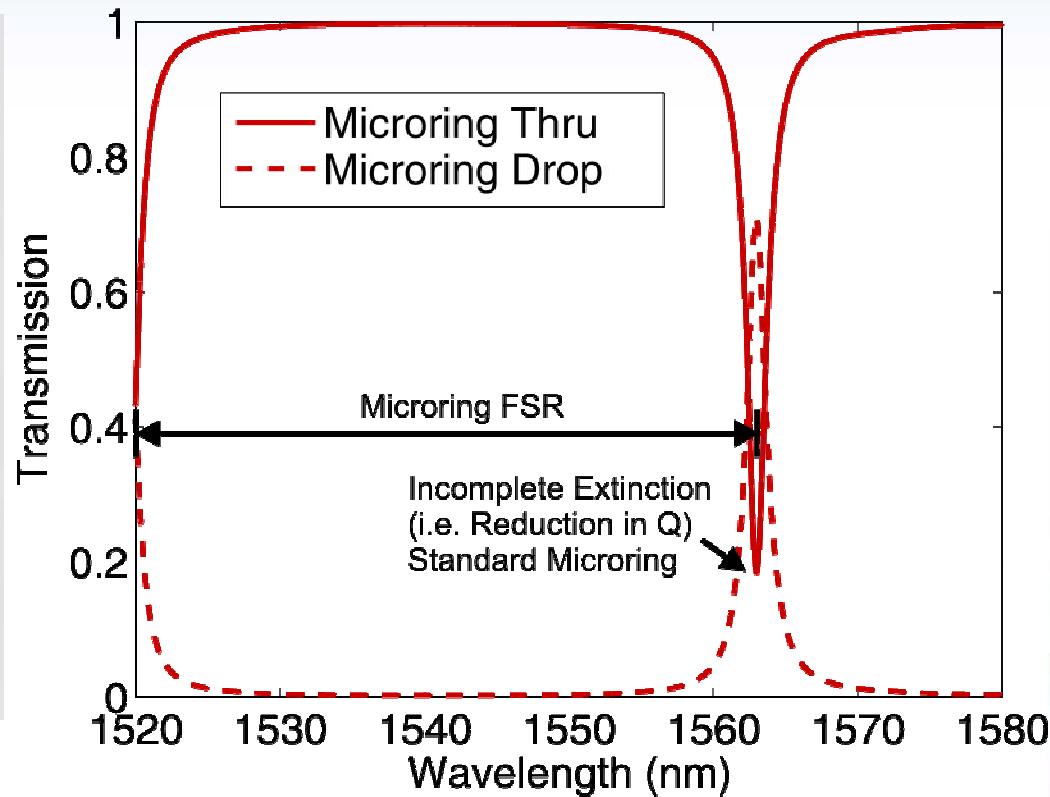
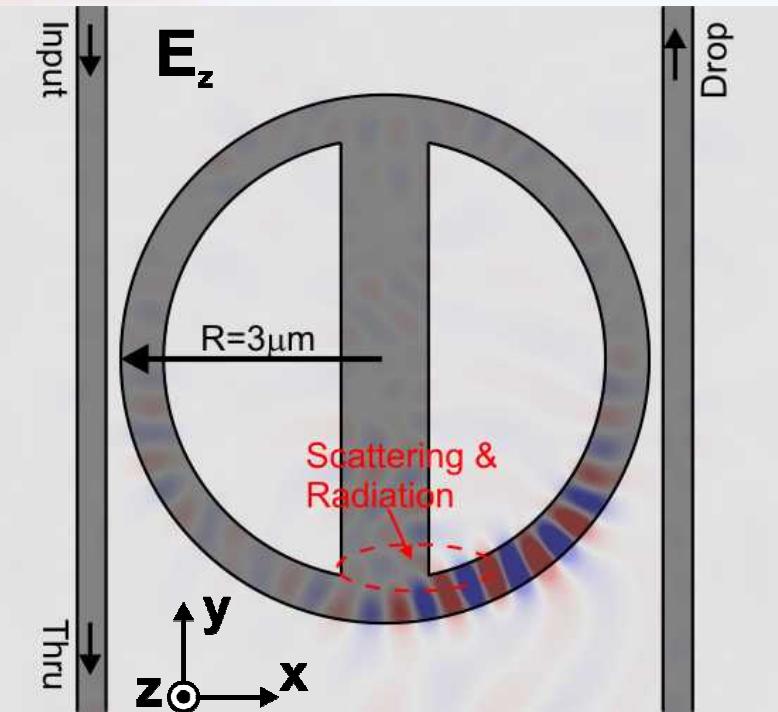
Experimentally Observed Microdisk FSR



Results

- As expected, microdisk propagates higher order modes corrupting FSR and limiting the available line bandwidth
- Can be fixed with a microring, but how do you make electrical contact?

What about Directly Contacting a Microring?



Results

- Microrings enable a recovery of the full Free Spectral Range
- However, the contact leads to scattering and a reduction in Q
- Can we modify the ring geometry to enable contact without loss?

An Adiabatic Bend: Contact without Radiation

Principle: Slow perturbations ($\Delta\beta/\kappa \gg 1$) do not result in coupled power

$$P(L) \propto \left| \frac{\kappa}{\Delta\beta} \right|^2 [1 - \cos(\Delta\beta L)]$$

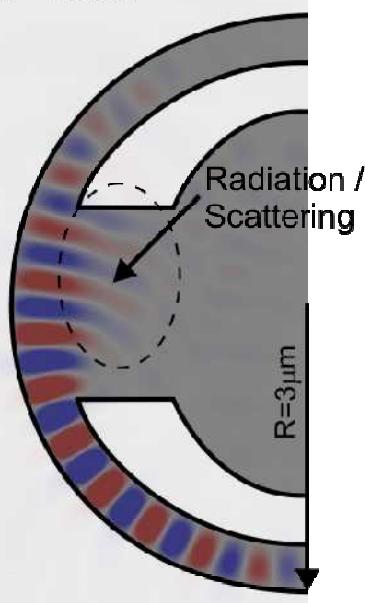
Thought: So, what if we introduce an adiabatic taper into a bend?

Simple Contact

Transmission = 64%

Loss = 36%

E_z

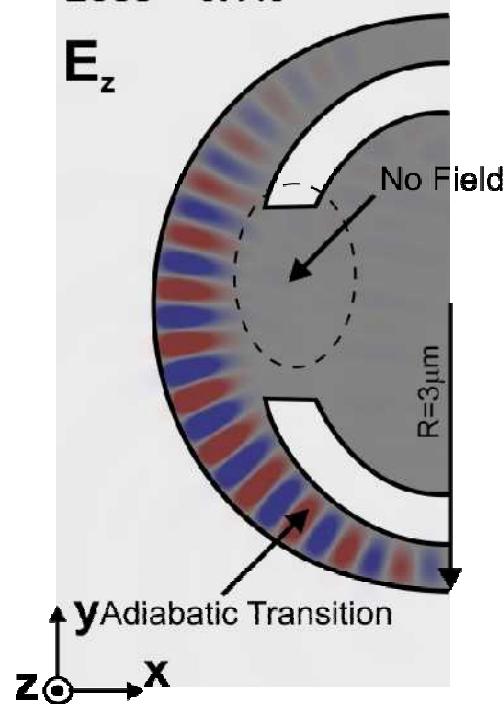


Adiabatic Bend

Transmission = 99.9%

Loss = 0.1%

E_z

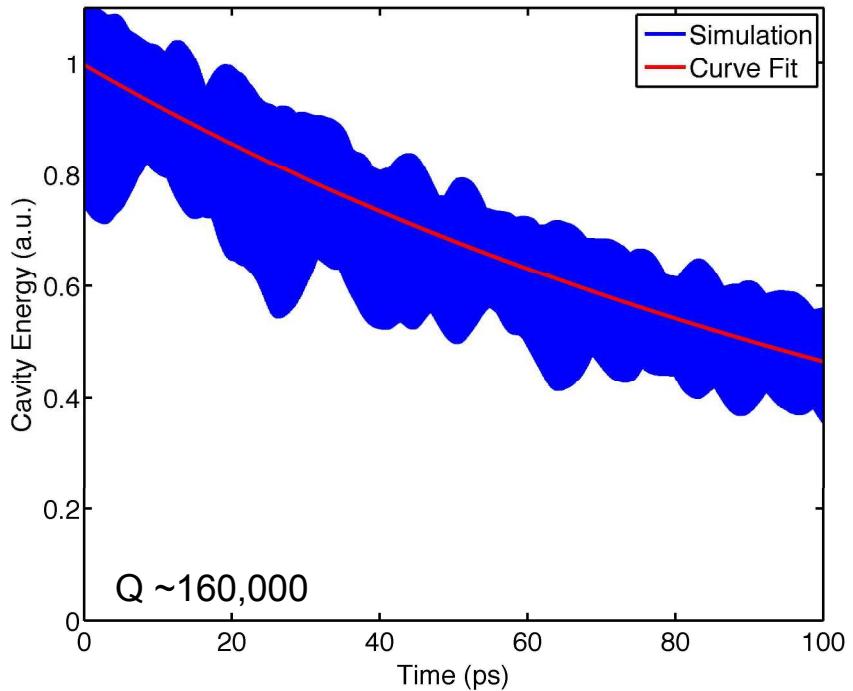
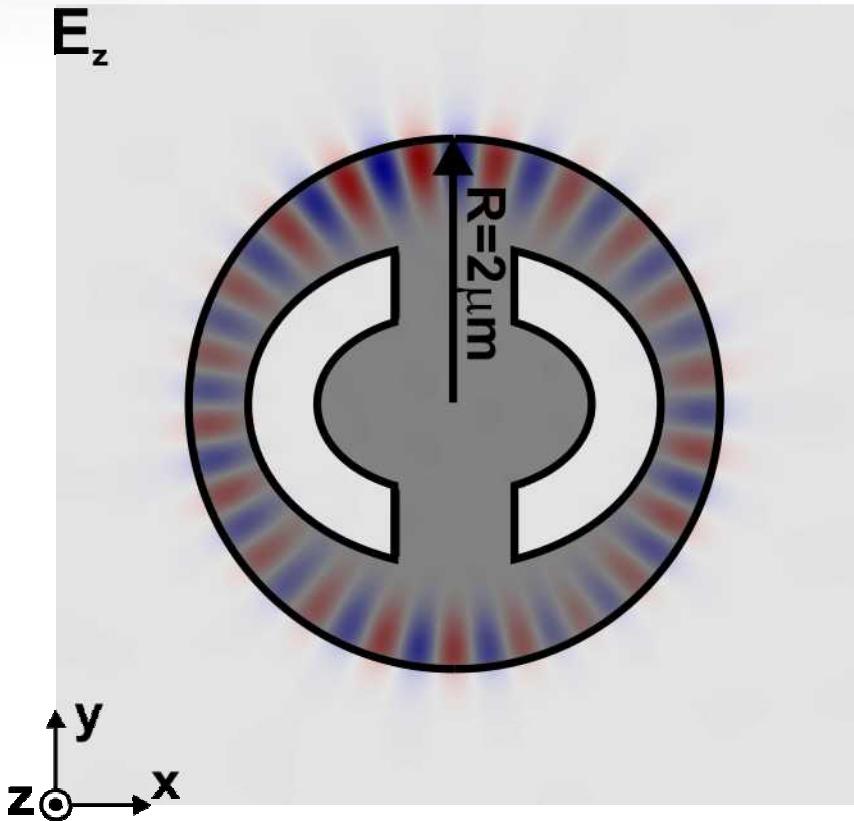


Results

- Adiabatic bend reduces losses from 36% to 0.1%
- Surprising how rapidly "adiabatic" transition is made (enabled by large difference in propagation rates between modes)



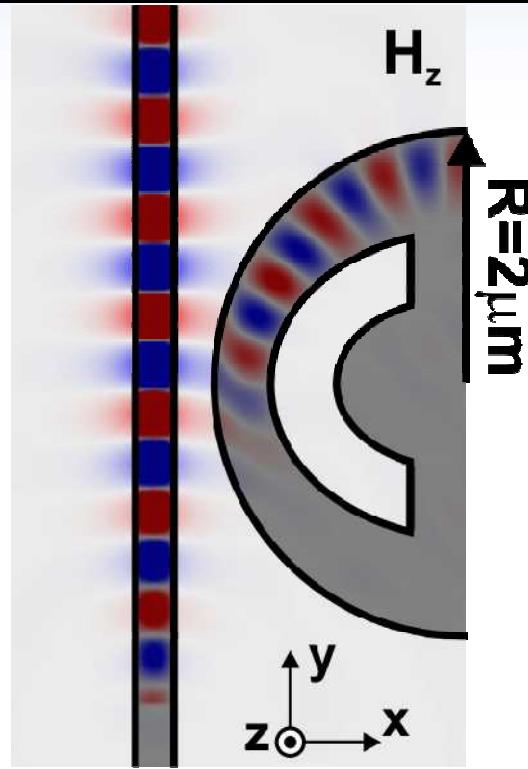
Adiabatic Microring-Resonator Q



Results

- Internal Q's exceeding 10^5 are possible in small adiabatic microrings
- Q's exceeding 10^6 are likely by iterating on designs

Coupling Losses: Essentially Eliminated



Coupling = 1.5%
Loss = 0.16%

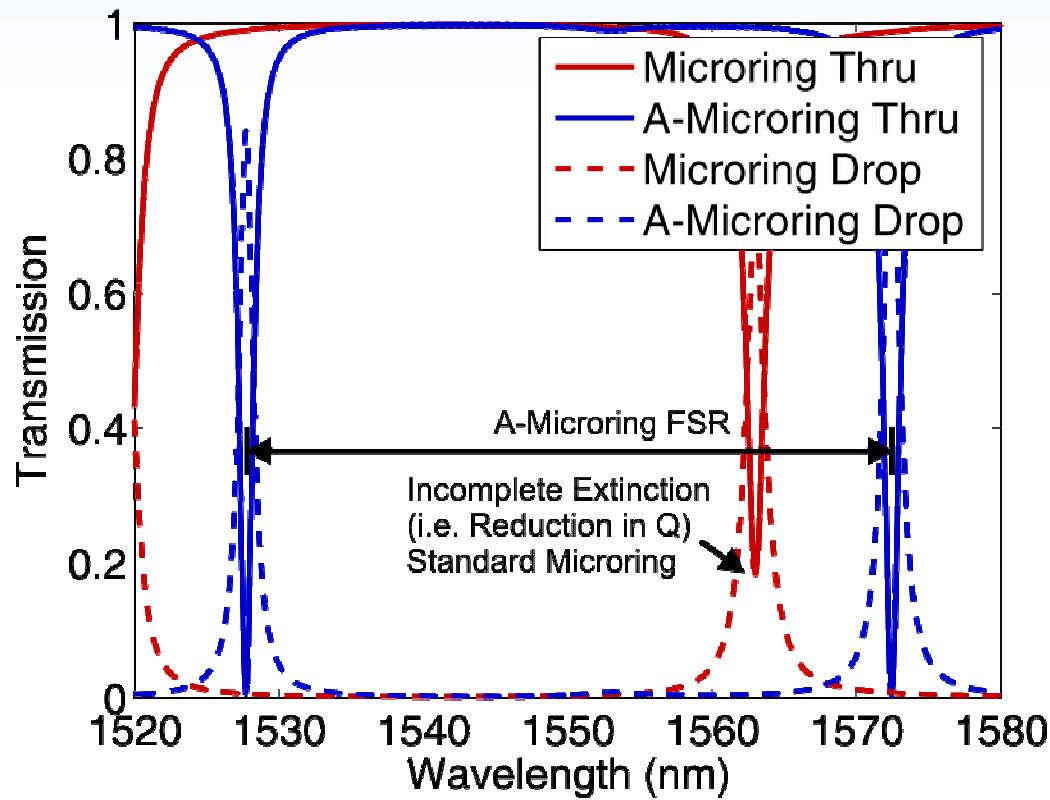
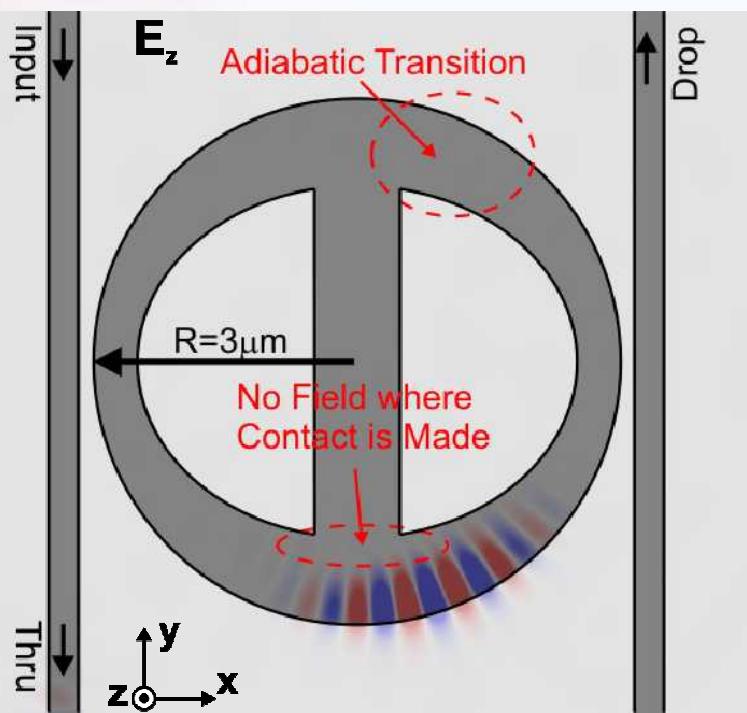
Approach / Results

- Higher order modes are eliminated in coupling region \rightarrow lossless coupling
- Narrower bus than ring waveguide used to mode-match / suppress coupling to lossy supermodes with the structure*,**

*M. R. Watts, PhD MIT Thesis (2005)

M.A. Popović et al., Opt. Lett., **31, pp. 2571-2573 (2006)

Free Spectral Range: Fully Recovered

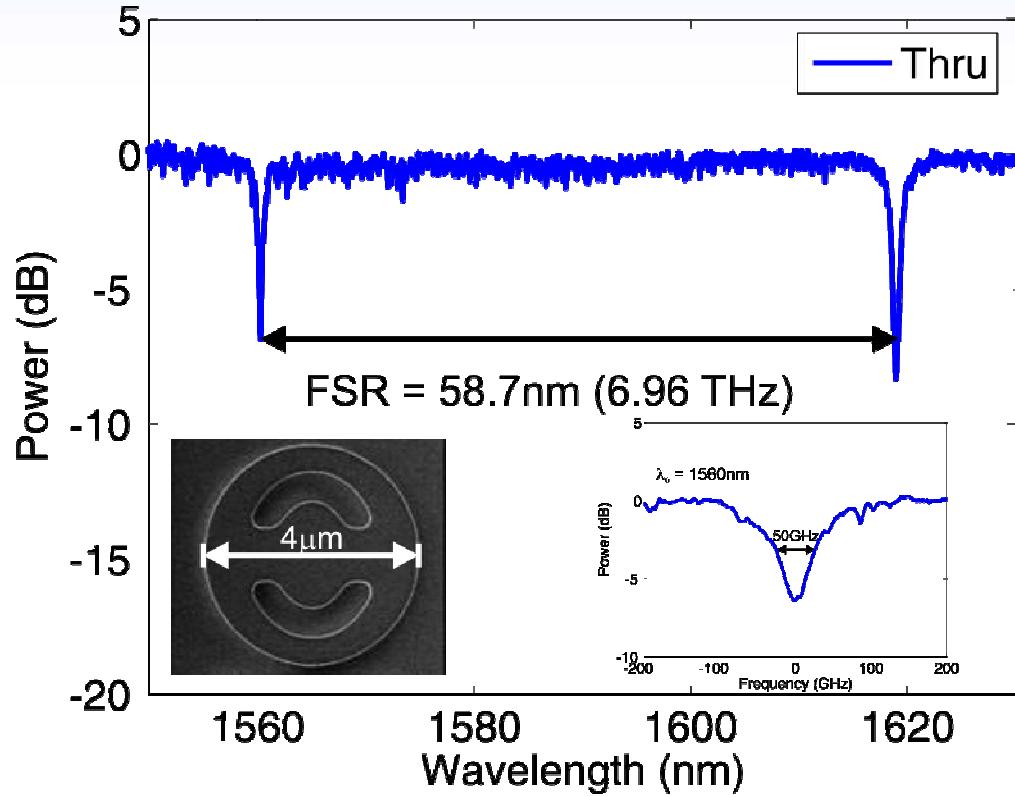
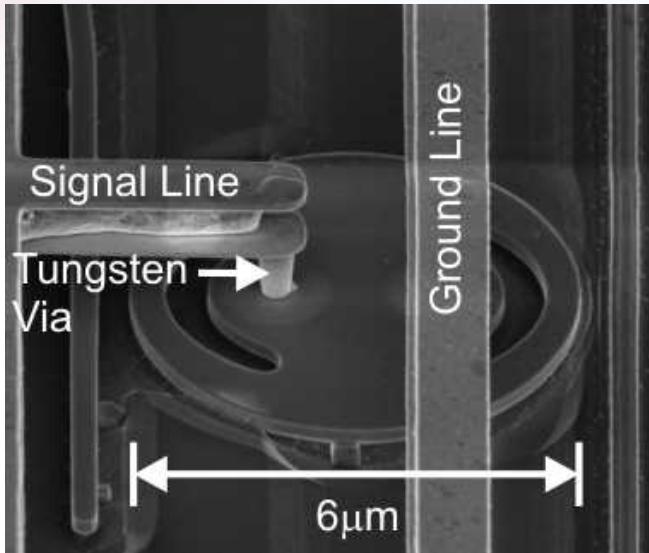


Results

- Adiabatic microrings enable a recovery of the full Free Spectral Range without inducing scattering and loss



Adiabatic Microring: Experimental Results



Results

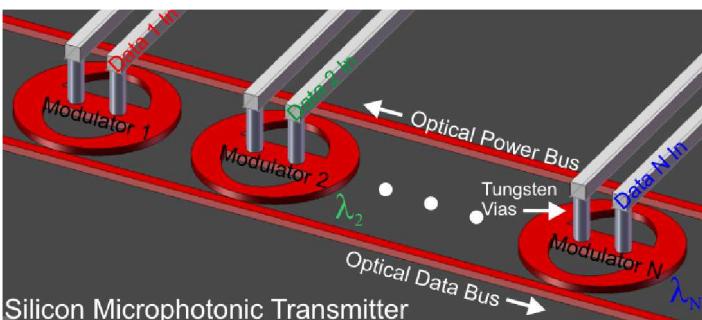
- Uncorrected 6.96THz Free-Spectral-Range
- Eliminated higher order modes without significant loss ($Q_{ext} \sim 4000$)
- Slight reduction in Q due to fabrication bias (i.e. loss of ~ 100 nm)
- Electrically active, 4 μm rings currently have insufficient Q, 6 μm rings have high-Q, testing now . . .

Summary and Future Outlook

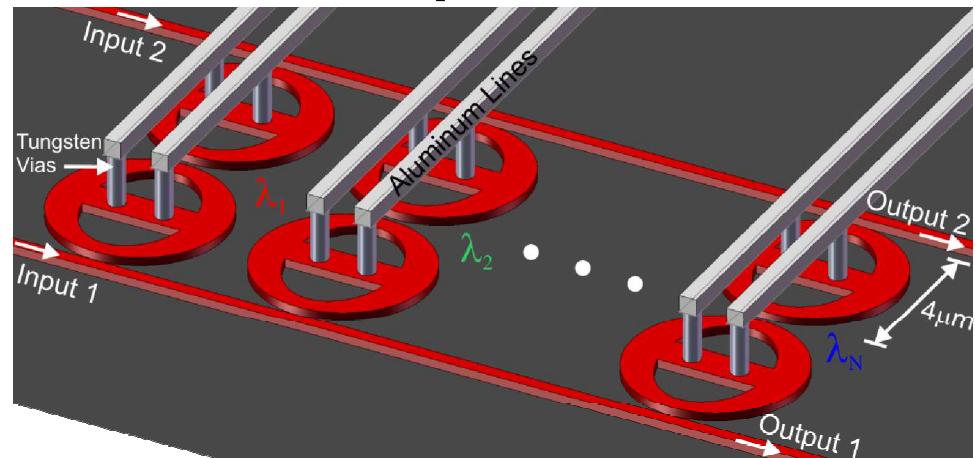
Modulators

- Demonstrated error-free, 10Gb/s NRZ data transmission (no pre-emphasis)
- Communications efficiency of 85fJ/bit (**100X less than electrical interchip**)
- Path to ~10fJ/bit with <2.5V drive is highly probable . . . enabling 1-Tb/s @10mW

1×N Silicon Modulators



1×N Bandpass Switches



Bandpass Switches

- First demonstrated electrically active high-speed (~2ns) silicon bandpass switch
- Can be driven with ~1V drive
- Did not require any post-fabrication trimming

Challenges Ahead

- Temperature control, fabrication tolerances, dense integration



Acknowledgements

FDTD Code: Christina Manolatou

Cylindrical Modesolver: Milos Popovic

Funding: Sandia LDRD and DARPA MTO (M. Haney and J. Shah)

